February 19, 2019

Business Segment: ELECTRONICS

MACDERMID ALPHA TO ESTABLISH A STRONG PRESENCE AT DEVICE PACKAGING CONFERENCE

(Waterbury, CT USA) - February 19, 2019 – MacDermid Alpha will exhibit total process solutions for emerging packaging at the IMAPS Conference, Fountain Hills, AZ, March 5-6, 2019.

MacDermid Alpha Electronics Solutions is a global leader in high performance semiconductor chemistries and assembly materials. Their Semiconductor Solutions division will highlight their MacDermid Enthone and Alpha brands. MacDermid Enthone will exhibit their family of MICROFAB products as well as launch their latest offering - MICROFAB TS 650, a high-speed tin silver bump metallization for bump, pillar and capping in wafer level packaging. They will also showcase their processes for IC substrates, including PackagePrep solderable finish for QFN sidewalls, and PackageBond leadframe adhesion promoter. The Alpha brand will present its expanding portfolio of products for solving semiconductor assembly challenges and reliability issues. The ATROX® series of hybrid silver sintering die attach adhesives, with their high thermal, low stress properties, are ideal die attach pastes and films for packages ranging from small all the way up to large die size. These featured products join Alpha's full line of high quality solder spheres, fluxes and solder paste materials for wafer, semiconductor, and SiP modules assemblies.

“The combined technology of the Alpha and MacDermid Enthone brands, provides advanced solutions that exceed aggressive packaging design requirements and enable greater device reliability,” said Leo Linehan, Vice President, Semiconductor Solutions. “Our attendance at IMAPS underscores our dedication to helping the industry reshape their strategies and best practices to adapt to the dramatically-changing semiconductor sector.”

OEMs, IDMs, wafer foundry engineers, tool suppliers, and OSATs should visit the MacDermid Alpha booth 43/44 to discuss the market demands. MacDermid Alpha's team of over twenty-five industry experts, including Mr. Linehan, will be available to discuss the challenges the semiconductor manufacturing sector faces as technology continues to push the limits of performance and miniaturization.

Contact: Deanna Cullen – Marketing Communications Manager, deanna.cullen@macdermidalpha.com